

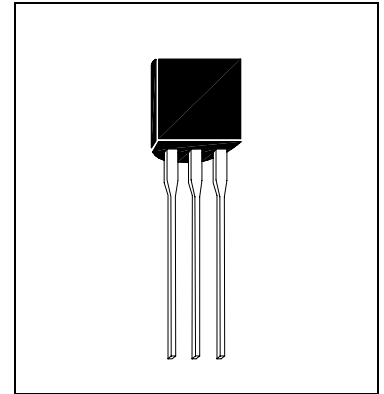


H2N7000

N-CHANNEL ENHANCEMENT MODE TRANSISTOR

Description

The H2N7000 is designed for high voltage, high speed applications such as switching regulators, converters, solenoid and relay drivers.



Absolute Maximum Ratings

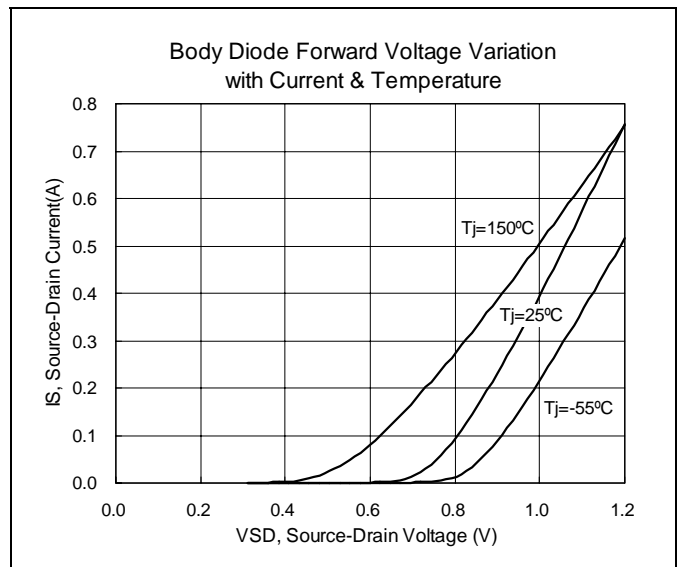
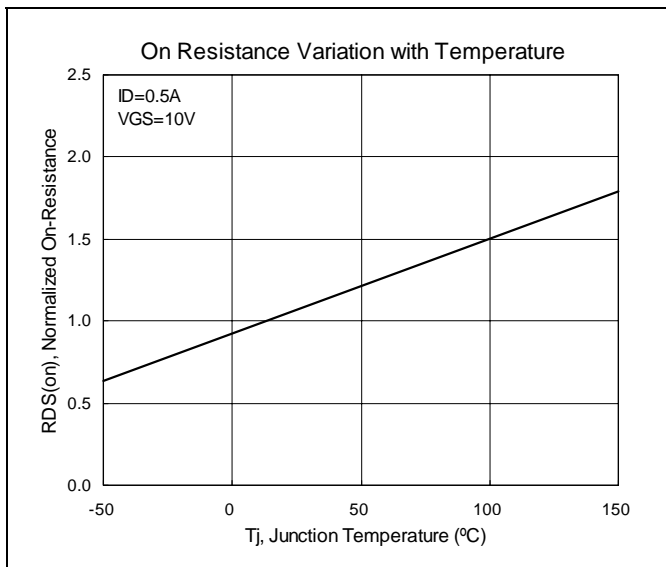
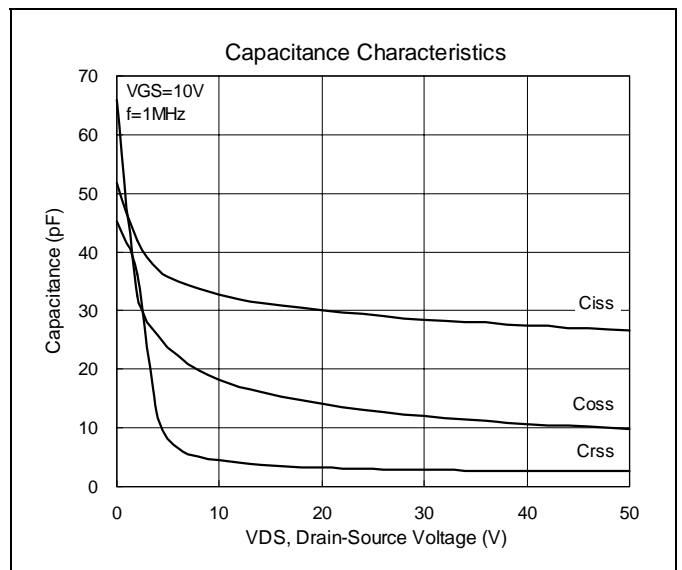
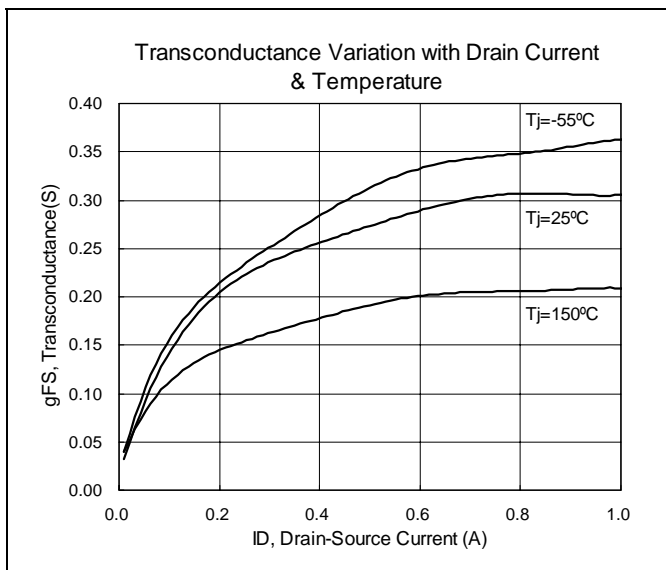
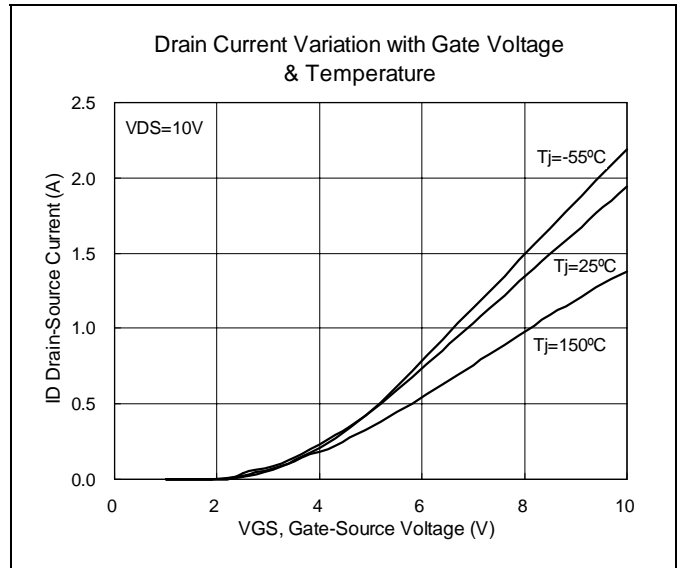
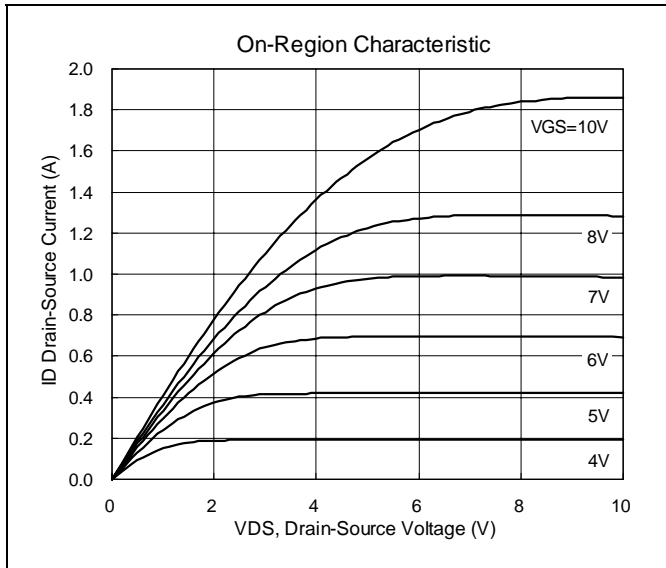
- Maximum Temperatures
 Storage Temperature -55 ~ +150 °C
 Junction Temperature +150 °C Maximum
- Maximum Power Dissipation
 Total Power Dissipation (Ta=25°C) 400 mW
- Maximum Voltages and Currents (Ta=25°C)
 BVDSS Drain to Source Voltage..... 60 V
 BVGSS Gate to Source Voltage 40 V
 ID Drain Current..... 200 mA

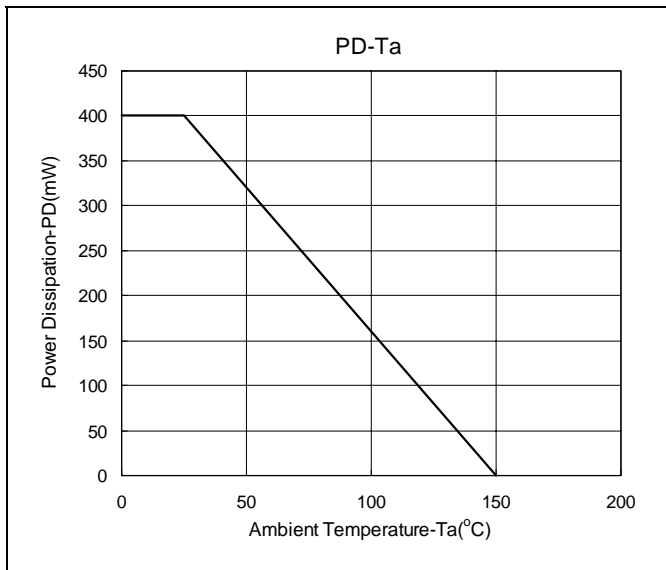
Characteristics (Ta=25°C)

Symbol	Min.	Max.	Unit	Test Conditions
VDSS	60	-	V	ID=10uA, VGS=0
IDSS	-	1	uA	VDS=48V
±IGSS	-	±10	nA	VGS=±15V
VGS(th)	0.8	3	V	VDS=3V, ID=1mA
ID(on)	75	-	mA	VGS=4.5V, VDS=10V
RDS(on)	-	5	Ω	VGS=10V, ID=0.5A
VDSS(on)1	-	2.5	V	VGS=10V, ID=0.5A
VDSS(on)2	-	0.4	v	VGS=4.5V, ID=75mA



Characteristics Curve







TO-92 Dimension

3-Lead TO-92 Plastic Package
 HSMC Package Code : A

Marking :

HSMC Logo → □ □ □ □ ← Product Series
 Part Number → □ □ □ □ □ □
 Date Code → □ □ □ □ □ □ ← Rank
 Laser Mark

HSMC Logo
 Product Series
 Part Number → □ □ □ □ □ □
 Ink Mark

Style : Pin 1.Source 2.Gate 3.Drain

*:Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1704	0.1902	4.33	4.83	G	0.0142	0.0220	0.36	0.56
B	0.1704	0.1902	4.33	4.83	H	-	*0.1000	-	*2.54
C	0.5000	-	12.70	-	I	-	*0.0500	-	*1.27
D	0.0142	0.0220	0.36	0.56	$\alpha 1$	-	*5°	-	*5°
E	-	*0.0500	-	*1.27	$\alpha 2$	-	*2°	-	*2°
F	0.1323	0.1480	3.36	3.76	$\alpha 3$	-	*2°	-	*2°

Notes : 1.Dimension and tolerance based on our Spec. dated Apr. 25,1996.
 2.Controlling dimension : millimeters.
 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material :

- Lead : 42 Alloy ; solder plating
- Mold Compound : Epoxy resin family, flammability solid burning class:UL94V-0

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